

MCBC Series



- Microprocessor based burst-fire controller / SSR
- Ratings from 25A to 90A @ 48-530 VAC
- Low-voltage, current, or potentiometer control
- Output status indicator
- Separate output enable / disable control
- Two time-base periods available
- For use with resistive loads only

PRODUCT SELECTION

Control Voltage	25 A	50 A	90 A
40-140 VAC	MCBC1225	MCBC1250	MCBC1290
180-280 VAC	MCBC2425	MCBC2450	MCBC2490
300-530 VAC	MCBC4825	MCBC4850	MCBC4890

AVAILABLE OPTIONS



OUTPUT SPECIFICATIONS (voltage)

Description	120 V	240 V	480 V
Operating Voltage (47-63Hz) [Vrms]	48-140	180-280	300-530
Transient Overvoltage [Vpk]	400	600	1200
Maximum Off-State Leakage Current @ Rated Voltage [mArms]	5	7	12
Minimum Off-State dv/dt @ Maximum Rated Voltage [V/μsec] (2)	200	200	200

OUTPUT SPECIFICATIONS (current)

Description	25 A	50 A	90 A
Maximum Load Current (3) [Arms]	25	50	90
Minimum Load Current [mArms]	150	150	150
Maximum Surge Current (16.6ms) [Apk]	250	625	1200
Maximum On-State Voltage Drop @ Rated Current [Vpk]	1.6	1.6	1.6
Thermal Resistance Junction to Case (Rjc) [°C/W]	1.02	0.63	0.28
Maximum I ² t for Fusing (8.3 msec) [A ² sec]	260	1620	6000

INPUT SPECIFICATIONS ⁽¹⁾

Description	DC Control
Control Voltage Range (VDC)	8-32 VDC
Input Current Range [mA] [P1]	28-30 VDC
Nominal Input Impedance [Ohms] [P3]	30K
Control Must Operate Voltage "On" [VDC][P3]	5-32
Control Must Release Voltage "Off" [VDC][P3]	0-4
Control Input Current [mA][P3]	0-1.25
PLV Range Option A [VDC][P4] ⁽²⁾	0-5
PLV Range Option B [VDC][P4] ⁽²⁾	0-7
PLV Range Option C [VDC][P4] ⁽²⁾	0-10
PLV Range Option D [VDC][P4] ⁽²⁾	4-20
Nominal Input Impedance Option A,B,C[ohms][P4]	20-K
Nominal Input Impedance Option D [ohms][P4]	220

OUTPUT STATUS FUNCTIONS

Conditions	LED
Initial Logic Supply On	Flash Once
Load Voltage Missing / Load Open (w/control disabled)	Flash Once Intermittently
Load Voltage Missing / Load Open (w/control enabled)	Flash Twice Intermittently
Analog Input < Threshold	Off
Analog Input < Threshold < max	Varying On/Off
Analog Input > max	On, Bright

GENERAL SPECIFICATIONS

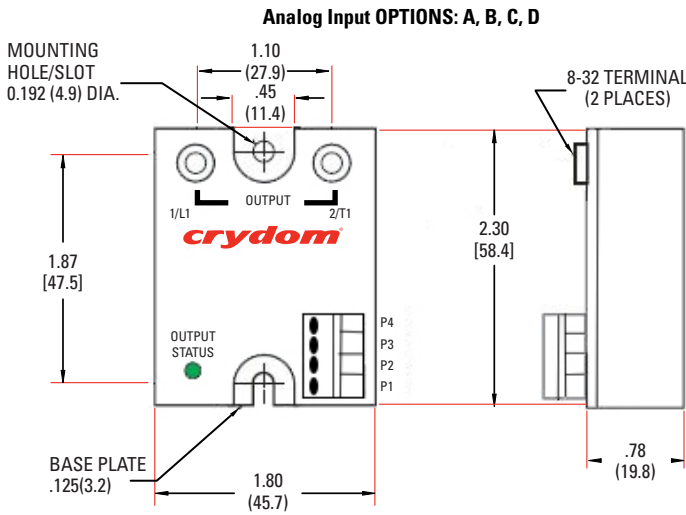
Description	Parameters
Dielectric Strength, Input/Output/Base (50/60Hz)	4000 VRMS
Minimum Insulation Resistance (@ 500 VDC)	10 ⁹ Ohm
Maximum Capacitance, Input/Output	10 pF
Ambient Operating Temperature Range	-20 to 80°C
Ambient Storage Temperature Range	-40 to 125 °C
Weight (typical)	3.0 oz (86.5g)
Encapsulation	Thermally conductive Epoxy
Terminals-Power	Screws and Saddle Clamps Furnished, Unmounted
Terminals-Control	Barrier Strip Screw Terminals
Recommended Terminal Screw Torque Range:	8-32 Screws -20 in. lbs.(Screws dry without grase)

GENERAL NOTES

- (1) Voltages are reference to GND (Ground = 0 VDC) P2
- (2) PLVI voltage can go up to max. supply voltage without damage

MECHANICAL SPECIFICATIONS

Tolerances: ± 0.02 in / 0.5 mm
 All dimensions are in: inches [millimeters]



THERMAL DERATE INFORMATION



WIRING DIAGRAM



Electrical Connections



OUTPUT VS ANALOG INPUT SIGNAL CURVES

Duty Cycle vs Input Signa P4



AGENCY APPROVALS, CONFORMANCES AND EMC

Agency Approvals



Rev. 121012

⚠ DANGER / PELIGRO / DANGER /GEFAHR / PERICOLO / 危險

<p>HAZARD OF ELECTRIC SHOCK, EXPLOSION, OR ARC FLASH.</p> <ul style="list-style-type: none"> • Disconnect all power before installing or working with this equipment. • Verify all connections and replace all covers before turning on power. <p>Failure to follow these instructions will result in death or serious injury.</p>	<p>RIESGO DE DESCARGA ELECTRICA O EXPLOSION.</p> <ul style="list-style-type: none"> • Desconectar todos los suministros de energia a este equipo antes de trabajar con este equipo. • Verificar todas las conexiones y colocar todas las tapas antes de energizar el equipo. <p>El incumplimiento de estas instrucciones puede provocar la muerte o lesiones serias.</p>	<p>RISQUE DE DESCARGE ELECTRIQUE OU EXPLOSION</p> <ul style="list-style-type: none"> • Eteindre toutes les sources d'énergie de cet appareil avant de travailler dessus de cet appareil • Vérifier tous connections, et remettre tous couverts en place avant de mettre sous <p>De non-suivi de ces instructions provoquera la mort ou des lésions sérieuses.</p>	<p>GEFAHR EINES ELEKTRISCHE N SCHLAGES ODER EINER EXPLOSION.</p> <ul style="list-style-type: none"> • Stellen Sie jeglichen Strom ab, der dieses Gerät versorgt, bevor Sie an dem Gerät Arbeiten durchführen • Vor dem Drehen auf Energie alle Anschlüsse überprüfen und alle Abdeckungen ersetzen. <p>Unterlassung dieser Anweisungen können zum Tode oder zu schweren Verletzungen führen.</p>	<p>RISCHIO DI SCOSSA ELETTRICA O DELL'ESPLOSIONE.</p> <ul style="list-style-type: none"> • Spenga tutta l'alimentazione che fornisce questa apparecchiatura prima di lavorare a questa apparecchiatura • Verificare tutti i collegamenti e sostituire tutte le coperture prima dell'accensione <p>L'omissione di queste istruzioni provocherà la morte o lesioni serie</p>	<p>存在电击、爆炸或电弧闪烁危险</p> <ul style="list-style-type: none"> • 在操作此设备之前请先关闭电源。 <p>若不遵守这些说明,可能会导致严重的人身伤害甚至死亡。</p>
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⚠ WARNING / AVERTISSEMENT / WARNUNG /ADVERTENCIA / AVVERTENZA / 警告

<p>RISK OF MATERIAL DAMAGE AND HOT ENCLOSURE</p> <ul style="list-style-type: none"> • The product's side panels may be hot, allow the product to cool before touching. • Follow proper mounting instructions including torque values. • Do not allow liquids or foreign objects to enter this product. <p>Failure to follow these instructions can result in serious injury, or equipment damage.</p>	<p>RISQUE DE DOMMAGE MATERIEL ET DE SURCHAUFFE DU BOITIER</p> <ul style="list-style-type: none"> • Les panneaux latéraux du produit peuvent être chauds. Laisser le produit refroidir avant de le toucher. • Respecter les consignes de montage, et notamment les couples de serrage. • Ne pas laisser pénétrer de liquide ni de corps étrangers à l'intérieur du produit. <p>Le non-respect de cette directive peut entraîner, des lésions corporelles graves ou des dommages matériels.</p>	<p>GEFAHR VON MATERIALSCHÄDEN UND GEHÄUSEERHITZUNG</p> <ul style="list-style-type: none"> • Die Seitenwände können heiß sein. Lassen Sie das Produkt abkühlen, bevor Sie es berühren. • Beachten Sie die Montageanweisungen, • Führen Sie keine Flüssigkeiten oder Fremdkörper in das Produkt ein. <p>Die Nichtbeachtung dieser Anweisung kann Körperverletzung oder Materialschäden zur Folge haben.</p>
<p>RIESGO DE DAÑOS MATERIALES Y DE SOBRECALENTAMIENTO DE LA UNIDAD</p> <ul style="list-style-type: none"> • Los paneles laterales del producto pueden estar calientes. Esperar que el producto se enfríe antes de tocarlo. • Respetar las instrucciones de montaje, y en particular los pares de apretado. • No dejar que penetren líquidos o cuerpos extraños en el producto. <p>Si no se respetan estas precauciones pueden producirse graves lesiones, daños materiales.</p>	<p>RISCHIO DI DANNI MATERIALI E D'INVOLUCRO CALDO</p> <ul style="list-style-type: none"> • I pannelli laterali dell'apparecchio possono scottare; lasciar quindi raffreddare il prodotto prima di toccarlo. • Seguire le istruzioni di montaggio corrette. • Non far entrare liquidi o oggetti estranei in questo apparecchio. <p>La mancata osservanza di questa precauzione può causare gravi rischi per l'incolumità personale o danni alle apparecchiature.</p>	<p>材料损坏和高温外壳的危险性</p> <ul style="list-style-type: none"> • 产品的一侧面板可能很热, 在其冷却前请不要触碰。 • 遵照正确的安装说明, 包括扭矩值。 • 请勿让液体及其他异物进入本产品。 <p>如不能正确执行这些操作说明, 极有可能造成严重人体伤害或者设备的损坏。</p>

ANNEX - ENVIROMENTAL INFORMATION

The environmental information disclosed in this annex including the EIP Pollution logo are in compliance with People’s Republic of China Electronic Industry Standard SJ/T11364 – 2006, Marking for Control of Pollution Caused by Electronic Information Products.

Part Name	Toxic or hazardous Substance and Elements					
	Lead (Pb)	Mercury (Hg)	Cadmium (Cd)	Hexavalent Chromium (Cr (VI))	Polybrominated biphenyls (PBB)	Polybrominated diphenyl ethers (PBDE)
Semiconductor die	X	○	○	○	○	○
Solder	X	○	○	○	○	○

附件 - 环保信息

此附件所标示的包括电子信息产品污染图标的环保信息符合中华人民共和国电子行业标准 SJ/T11364 - 2006, 电子信息产品污染控制标识要求。

部件名称	有毒有害物质或元素					
	铅 (Pb)	汞 (Hg)	镉 (Cd)	六价铬 (Cr (VI))	多溴联苯 (PBB)	多溴二苯醚 (PBDE)
半导体芯片	X	○	○	○	○	○
焊接点	X	○	○	○	○	○

